

LATEST NEWS

[ESCC QPL December 2017 NEW FORMAT](#)



The ESCC QPL December was published with 5 extensions and 4 amendments.

The new format (first released in October 2017) of the document is more user-friendly and allows for easy navigation across its sections. QPL users will find more easily what they may be looking for. The new QPL includes as well all the direct automatic links to the procurement specifications and manufacturers' information as posted in ESCIES. For more information please click [HERE](#)



[NEW ESCC Process Capability Approval](#)

3D Plus is now certified in accordance with ESCC 2566001 for its 3D Staking Technology Modules!!



NEW ESCC Specifications Published:

October 2017: A NEW ESCC Basic Specification **REQUIREMENTS FOR THE PROCESS CAPABILITY APPROVAL FOR MANUFACTURING LINES OF NON-HERMETIC MICROELECTRONIC MODULES** was published, ESCC **2566001 issue 1**. Please click [HERE](#) for more information



ECSS-Q-ST-70-38rev1 (15 September 2017) Published

This Standard prescribes requirements for electrical connections of leadless and leaded surface mounted devices (SMD) on spacecraft and associated equipment, utilising a range of substrate assemblies and employing solder as the interconnection media. Please click [HERE](#) to view the document

Successfully completed ESCC Qualification AUDITS

The ESCC Executive performs an audit of the manufacturer's design, production and test facilities. This combines a Quality Management System audit and a manufacturing line survey.

Recently ESA successfully preformed audits during 2017 at the following Qualified Manufacturers:

4 in the UK: AVX Ltd., TE Connectivity (Tyco Electronics Ltd.), W.L. Gore (UK), Teledyne Reynolds

6 in France: Atmel Microchip, Exxelia Magnetics (Microspire), Leach, Minco, Vishay Sfernice, 3D Plus



3 in Germany: Tesat, RHe Microsystems, Vishay Draloric

1 in Belgium: TAS

1 in Italy: IRCA-RICA

2 in Switzerland: IST, Diamond

UPCOMING EVENTS



[ESCC Training Course](#)

The next ESCC Training Course will take place at ESA/ESTEC in Noordwijk on **January 11th, 2018!** For more information, please click [HERE](#)



[Workshop on Innovative Technologies for Space Optics](#)

This workshop focuses on selected topics on innovative optical technologies identified as enabling for future missions or critical in the improvement of current mission concepts. 12- 16 February 2018 at ESA/ESTEC in Noordwijk. For more information, please click [HERE](#)

RECENTLY PUBLISHED ESCC SPECIFICATION

Up-Issued ESCC Specifications published since 15th November 2017

Number	Title
21001	DESTRUCTIVE PHYSICAL ANALYSIS OF EEE COMPONENTS
21700	General Requirements for the Marking of ESCC Components
3001	Generic Specification for Capacitors Fixed Ceramic Dielectric Types I and II
3009	Generic Specification for Capacitors Fixed Chips Ceramic Dielectric Types I and II
3001/030	Capacitors Fixed Ceramic Dielectric Type II High Capacitance 50 to 500V, based on case styles BR,CV and CH
3001/033	Capacitors Fixed Ceramic Dielectric Type I High Voltage 1.0 to 5.0kV, based on case styles VR,CV & CH
3001/034	Capacitors Fixed High Ceramic Dielectric Type II High Voltage 1.0 to 5.0kV, based on case styles VR,CV & CH
3001/037	Capacitors, Fixed, Multiple Layer, Ceramic Dielectric, Type II, Based on Type CNC31, CNC32, CNC33 and CNC34

3009/003	Capacitors Fixed Chips Ceramic Dielectric Type I, based on type 0805 Capacitors Fixed Chips Ceramic Dielectric Type I, based on type 1210
3009/004	Capacitors Fixed Chips Ceramic Dielectric Type I, based on type 1210
3009/005	Capacitors Fixed Chips Ceramic Dielectric Type I, based on type 1812
3009/006	Capacitors Fixed Chips Ceramic Dielectric Type I, based on type 2220
3009/008	Capacitors Fixed Chips Ceramic Dielectric Type II, based on type 0805
3009/009	Capacitors Fixed Chips Ceramic Dielectric Type II, based on type 1210
3009/010	Capacitors Fixed Chips Ceramic Dielectric Type II, based on type 1812
3009/011	Capacitors Fixed Chips Ceramic Dielectric Type II, based on type 2220
3009/022	Capacitors Fixed Chips Ceramic Dielectric Type I, Based on type 1206
3009/023	Capacitors Fixed Chips Ceramic Dielectric Type II, based on type 1206
3009/034	Capacitors, Fixed, Chips, High Voltage (1 to 3kv), Ceramic Dielectric, Type II, based on types 1812 and 1825
3009/037	Capacitors, fixed, chips, dielectric ceramic type I, based on type 0603
3009/038	Capacitors, fixed, chips, ceramic dielectric type II, based on type 0603
3009/039	Capacitors, Fixed, Chips, Ceramic Dielectric, Type II with Flexible Terminations, Based on Types 0603 to 2220
3009/040	Capacitors, Fixed, Chips, Ceramic Dielectric, Type I with Flexible Terminations, Based on Types 0603 to 2220
3009/041	Capacitors, Fixed, Chips, Base Metal Electrode, Ceramic Dielectric, Type II, Based On Types 0402 To 2220
3009/042	Capacitors, Fixed, Chips, Ceramic Dielectric, Type I, based on type 0402
3009/043	CAPACITORS, FIXED, CHIPS, CERAMIC DIELECTRIC, TYPE II, BASED ON TYPE 0402

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